

GENERAL DESCRIPTION

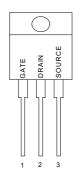
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

FEATURES

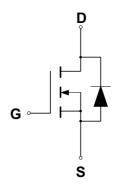
- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- ◆ I_{DSS} Specified at Elevated Temperature

PIN CONFIGURATION

TO-220/TO-220FP Front View



SYMBOL



N-Channel MOSFET



ABSOLUTE MAXIMUM RATINGS

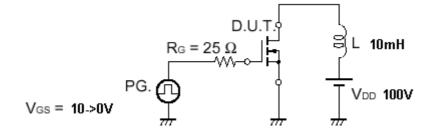
Rating	Symbol	Value	Unit
Drain to Current — Continuous	I _D	6.0	Α
- Pulsed	I _{DM}	18	
Gate-to-Source Voltage — Continue	V_{GS}	±20	V
Non-repetitive	V_{GSM}	±40	V
Total Power Dissipation	P _D		W
TO-220		125	
TO-220FP		45	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to 150	$^{\circ}$
Single Pulse Drain-to-Source Avalanche Energy $-$ T _J = 25° C			mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_{L} = 6A, L = 10mH, R_{G} = 25\Omega)$	E _{AS}	180	
Thermal Resistance — Junction to Case	θ_{JC}	1.0	°C/W
 Junction to Ambient 	θЈΑ	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	$^{\circ}\!\mathbb{C}$

- (1) VDD = 50V, ID = 6A
- (2) Pulse Width and frequency is limited by T_{J(max)} and thermal response

ORDERING INFORMATION

Part Number	Package		
IRF6N60	TO-220		
IRF6N60FP	TO-220 Full Pak		

TEST CIRCUIT



Test Circuit - Avalanche Capability



ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}C$.

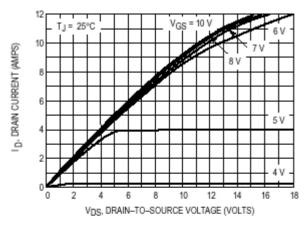
			IRF6N60			
Chara	Symbol	Min	Тур	Max	Units	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	600			V	
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		I _{DSS}				μA
$(V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V})$					100	
$(V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125^{\circ}\text{C})$					50	
Gate-Source Leakage Current-Forward		I _{GSSF}			100	nA
$(V_{gsf} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Reverse	•	I _{GSSR}			100	nA
$(V_{gsr} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		V _{GS(th)}	2.0		4.0	V
$(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V _G	_S = 10 V, I _D = 3.5A) *	R _{DS(on)}			1.2	Ω
Forward Transconductance (V _{DS} = 15 V	′, I _D = 3.0A) *	g FS	3.4			mhos
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}.$	C _{iss}		1498	2100	pF
Output Capacitance	$(v_{DS} - 25 \text{ v}, v_{GS} - 0 \text{ v},$ f = 1.0 MHz)	C _{oss}		158	220	pF
Reverse Transfer Capacitance	1 – 1.0 WH IZ)	C _{rss}		29	60	pF
Turn-On Delay Time	$(V_{DD} = 300 \text{ V}, I_D = 6.0 \text{ A},$	t _{d(on)}		14	30	ns
Rise Time	$V_{DD} = 300 \text{ V}, I_D = 6.0 \text{ A},$ $V_{GS} = 10 \text{ V}.$	t _r		19	40	ns
Turn-Off Delay Time	$V_{GS} = 10 \text{ V},$ $R_{G} = 9.1\Omega) *$	t _{d(off)}		40	80	ns
Fall Time	NG - 9.102)	t _f		26	55	ns
Total Gate Charge	$(V_{DS} = 300 \text{ V. } I_{D} = 6.0 \text{ A.}$	Q_g		35.5	50	nC
Gate-Source Charge	$(V_{DS} = 300 \text{ V}, I_D = 6.0 \text{ A},$ $V_{GS} = 10 \text{ V})^*$	Q_{gs}		8.1		nC
Gate-Drain Charge	V _{GS} - 10 V)	Q_{gd}		14.1		nC
Internal Drain Inductance		L _D		4.5		nH
(Measured from the drain lead 0.25"	from package to center of die)					
Internal Drain Inductance	Ls		7.5		nH	
(Measured from the source lead 0.25	" from package to source bond pad)					
SOURCE-DRAIN DIODE CHARACTEI	RISTICS					
Forward On-Voltage(1)	(1 - 6 0 4	V _{SD}		0.83	1.2	V
Forward Turn-On Time	$(I_S = 6.0 \text{ A},$ $d_{IS}/d_t = 100\text{A/µs})$	t _{on}		**		ns
Reverse Recovery Time	t _{rr}		266		ns	

^{*} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%

^{**} Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS



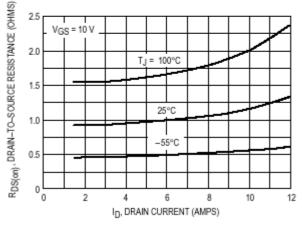
100°C 25°C 100°C 1

12

V_{DS} ≥ 10 V

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



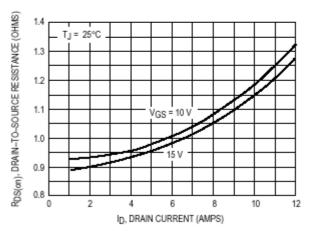
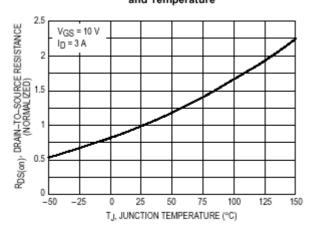


Figure 3. On–Resistance versus Drain Current and Temperature

Figure 4. On–Resistance versus Drain Current and Gate Voltage



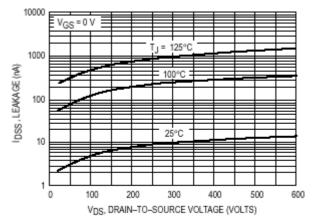
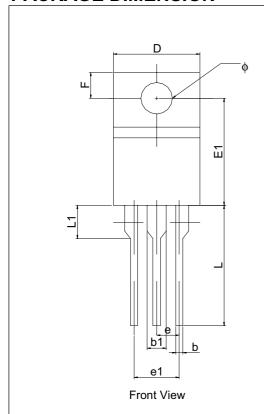


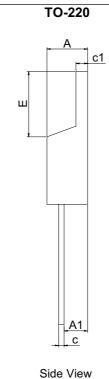
Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-To-Source Leakage Current versus Voltage



PACKAGE DIMENSION

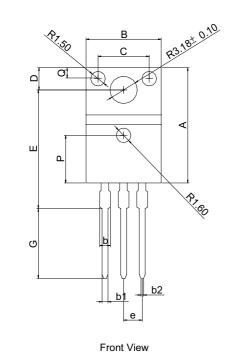


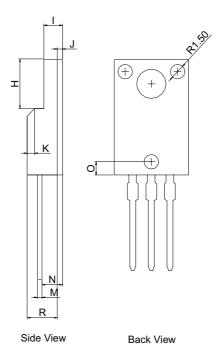


PIN 1: GATE PIN 2: DRAIN PIN 3: SOURCE

SYMBOLS DIMENSIONS IN MILLIMETERS		DIMENS	DIMENSIONS IN INCHS			
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	4.47		4.67	0.176		0.184
A1	2.52		2.82	0.099		0.111
b	0.71		0.91	0.028		0.036
b1	1.17		1.37	0.046		0.054
С	0.31		0.53	0.012		0.021
c1	1.17		1.37	0.046		0.054
D	10.01		10.31	0.394		0.406
E	8.50		8.90	0.335		0.350
E1	12.06		12.46	0.475		0.491
е		2.54			0.100	
e1	4.98		5.18	0.196		0.204
F	2.59		2.89	0.102		0.114
L	13.40		13.80	0.528		0.543
L1	3.56		3.96	0.140		0.156
ф	3.79		3.89	0.149		0.153

TO-220FP





Back View

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHS		
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	15.67		16.07	0.617		0.633
В	9.96		10.36	0.392		0.408
С		7.00			0.275	
D	3.20		3.40	0.126		0.134
Е	15.60		16.00	0.614		0.630
G	9.45		10.05	0.372		0.396
Н	6.48		6.88	0.255		0.279
- 1	2.34		2.74	0.092		0.108
J		0.70			0.028	
K		1.00			0.039	
М	0.45		0.60	0.018		0.024
N	2.56		2.96	0.101		0.117
0		1.80			0.071	
P		6.50			0.256	
Q		1.50			0.059	
R	4.50		4.90	0.177		0.193
b			1.47			0.058
b1	0.70		0.90	0.028		0.035
b2	0.25		0.45	0.010		0.018
e		2.54			0.100	